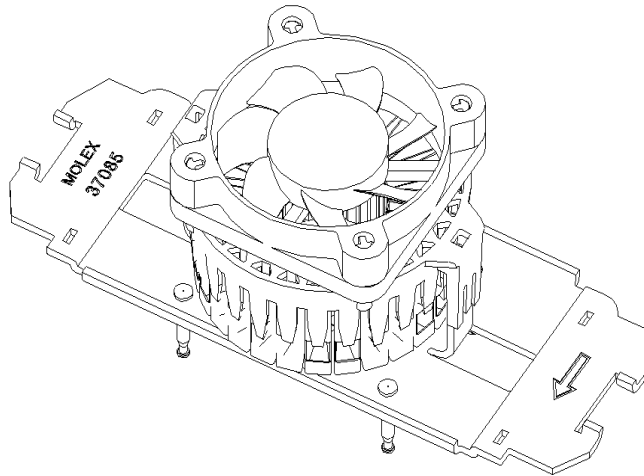


**molex** Thermal Acoustic Products  
**Radial Fin™ for SECC2**  
**Heat Transfer Device**

The Radial Fin for SECC2 is a high-performance active heat transfer device designed to replace traditional extrusions. Since Radial Fin cools the SECC2 with increased volumetric efficiency over typical extrusion heat sinks, microprocessors can be cooled with lower airflow. Lowering the airflow requirements reduces the fan noise and enables the system designer to develop a quieter PC.

The Radial Fin uses Molex's patent pending radial folded fin technology, allowing a full 360° of airflow. The Radial Fin heat sink snaps easily onto the microprocessor with a standard, or new low-profile, attachment clip.



**Innovative Mechanical Design**

- Based on Molex's patent pending radial folded fin technology
- 360° airflow translates into a high performance, low noise and lightweight heat sink
- Works in both the pressurizing and evacuating fan mode

**Lightweight**

- At 110g, the Radial Fin is lower weight than a typical extrusion
- Mechanical/shock vibration and center of gravity requirements are met with significantly more design margin
- Does not require heat sink supports to pass mechanical and vibration requirements

**High Thermal Efficiency**

- Increased volumetric efficiency over typical extrusion heat sinks
- Less air flow is required for comparable thermal performance, resulting in significantly lower audible noise emissions. (25dBA nominal)

**Attachment**

Radial Fin mounts onto the SECC2 module with a simple back clip. Molex offers a fixture to aid in assembly and to ensure consistent attachment during high-volume production.

**Thermal Performance**

Molex system level tests have shown a case to ambient thermal resistance as low as 0.64°C/W.

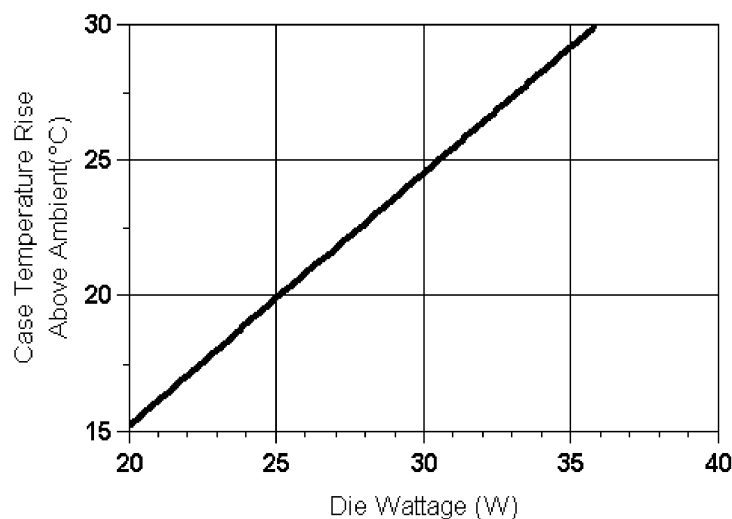
**Installation**

The Radial Fin uses a separate attachment clip, available in standard or low profile versions. To attach the Radial Fin for SECC2, remove the interface liner and place the heat sink onto the SECC2 module, passing the attachment pins through the module. Place the attachment clip over the pins, press down and slide the clip to engage all four of the pins. This can also be done with an application tool for high volume applications.

**Thermal Interface**

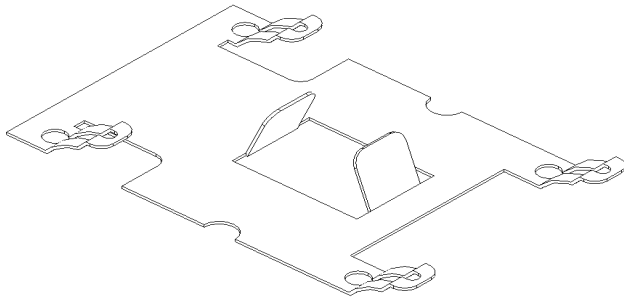
The Radial Fin for SECC2 comes with thermal interface applied. Custom interface material is available upon request.

**Thermal Performance vs. Die Wattage**  
 (Includes Interface Impedance)

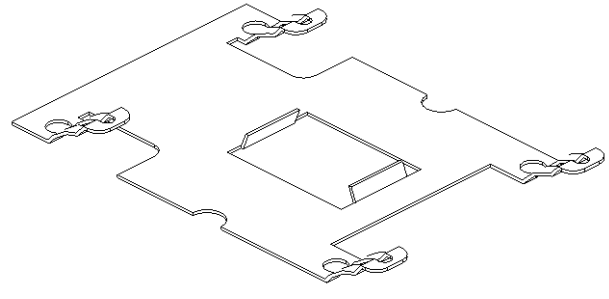


Based on using a Medium Speed Fan

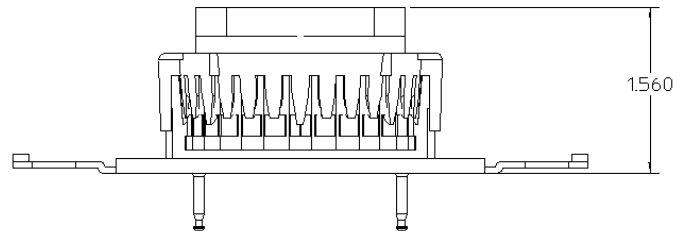
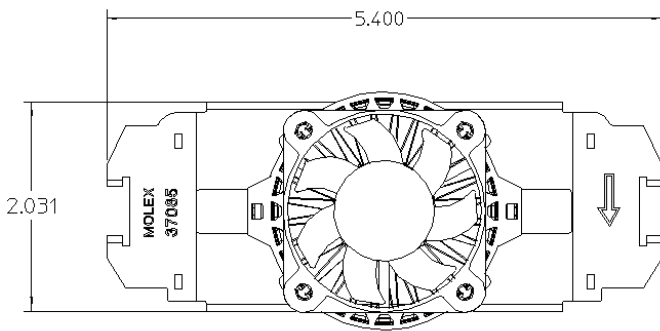
**molex® Thermal Acoustic Products**  
**Radial Fin™ for SECC2**  
**Heat Transfer Device**



**Standard Clip**



**Low Profile Clip**



Order No.	Description	Fan Speed*	Interface	Attachment Clip
37085-0001	Radial Fin for SECC2	Low Speed	Chomerics T725	Low Profile
37085-0007	Radial Fin for SECC2	Medium Speed	Chomerics T725	Low Profile
37085-0003	Radial Fin for SECC2	High Speed	Chomerics T725	Low Profile
37085-0101	Radial Fin for SECC2	Low Speed	Chomerics T725	Standard
37085-0102	Radial Fin for SECC2	Medium Speed	Chomerics T725	Standard
37085-0103	Radial Fin for SECC2	High Speed	Chomerics T725	Standard

\*Fan comes with 3-wire assembly, 292.10mm (11.50") overall length. Custom configurations available upon request.



*Bringing People & Technology Together, Worldwide<sup>SM</sup>*

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